

## Publikationen

- (2019): Projekt NePUMuk (Neue digitale Produktions- und Mikrostrukturierungstechnologien für Anwendungen bis 80 GHz). Abschlussbericht.
- (2019): Bare die connections via aerosol jet technology for millimeter wave applications. In: International Journal of Microwave and Wireless Technologies, vol. 11, no. Special Issue 5-6 (EuMW 2018 Special Issue (Part I)) [June], pp. 441-446. DOI: 10.1017/S1759078719000114.
- (2019): WR12 to planar transmission line transition on organic substrate. Invited Talk. In: 49th European Microwave Conference (EuMC), Paris, Frankreich.
- (2019): Zero-point clamping systems in optical production. In: Proceedings of SPIE 11171 (Sixth European Seminar on Precision Optics Manufacturing, 1117101 [April 9th-10th 2019, Teisnach]), Bellingham, WA, USA. DOI: 10.1117/12.2528774.
- (2019): WR12 to planar transmission line transition on organic substrate. In: Proceedings of the 49th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2019 (September 29-October 4, 2019; Paris, France). DOI: 10.23919/EuMC.2019.8910843.
- (2018): Bare Die Connections via Aerosol Jet Technology for Millimeter Wave Applications. In: Proceedings of the 48th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2018 (September 24-28, 2018; Madrid, Spain).
- (2018): Rechnergestützte Optimierung von galvanischen Kupferabscheideprozessen. Posterpräsentation. In: 5. Tag der Forschung, Deggenedorf.
- (2017): Projekt NePUMuk (Neue digitale Produktions- und Mikrostrukturierungstechnologien für Anwendungen bis 80 GHz). Projektbericht.
- (2017): Cost-Effective SIW Band-Pass Filters for Millimeter Wave Applications. In: Proceedings of the 47th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2017 (October 8-12, 2017, Nürnberg). DOI: 10.23919/EuMC.2017.8230878.
- (2016): Differential Wideband Interconnects for Organic Millimeter Wave Chip Packages. An effort to design an all-purpose RF chip package. In: Proceedings of the 11th European Microwave Integrated Circuits Conference 2016 (October 03-04 2016, London, UK).
- (2016): Differential Wideband Interconnects for Organic Millimeter Wave Chip Packages. An effort to design an all-purpose RF chip package. In: Proceedings of the 46th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2016 (October 03-07 2016, London, UK).
- (2015): Wideband RF interconnects for organic chip packages comparison of single ended and differential transitions. An effort to design an all-purpose RF chip package. In: Proceedings of the 45th European Microwave Conference (EuMC)/European Microwave Week (EuMW) 2015 (September 06-11 2015, Paris, France).
- (2013): Embedded Resistors for High Frequency Applications on Printed Circuit Boards. In: Proceedings of the 43rd European Microwave Conference, Nürnberg, 06.-11.10.2013.